



Docket No.: 0039-7632-0X

ASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

RE: Application Serial No.: 09/531,163

Applicants: Hiroyuki YANO, et al.

Filing Date: March 17, 2000

For: AQUEOUS DISPERSION, AQUEOUS DISPERSION  
FOR CHEMICAL MECHANICAL POLISHING USED  
FOR MANUFACTURE OF SEMICONDUCTOR  
DEVICES, METHOD FOR MANUFACTURE OF  
SEMICONDUCTOR DEVICES, AND METHOD FOR  
FORMATION OF EMBEDDED WIRING

Group Art Unit: 1765

Examiner: DEO, D.

SIR:

Attached hereto for filing are the following papers:

**Amendment and Request for Reconsideration (6 pp.)**  
**Certified English Translation**  
**Certified English Translation of Experiment Report (3 pp.)**  
**Experiment Report (3 pp.)**

Our check in the amount of \$0.00 is attached covering any required fees. In the event any variance exists between the amount enclosed and the Patent Office charges for filing the above-noted documents, including any fees required under 37 C.F.R. 1.136 for any necessary Extension of Time to make the filing of the attached documents timely, please charge or credit the difference to our Deposit Account No. 15-0030. Further, if these papers are not considered timely filed, then a petition is hereby made under 37 C.F.R. 1.136 for the necessary extension of time. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

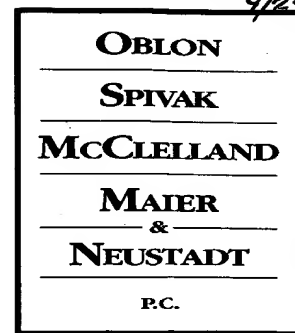
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TC 1700



DOCKET NO.: 0039-7632-0X

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF: :  
HIROYUKI YANO ET AL. : GROUP ART UNIT: 1765  
SERIAL NO: 09/531,163 :  
FILED: MARCH 17, 2000 : EXAMINER: DEO, D.

FOR: AQUEOUS DISPERSION, AQUEOUS  
DISPERSION FOR CHEMICAL  
MECHANICAL POLISHING USED  
FOR MANUFACTURE OF SEMI-  
CONDUCTOR DEVICES, METHOD  
FOR MANUFACTURE OF SEMI-  
CONDUCTOR DEVICES, AND  
METHOD FOR FORMATION OF  
EMBEDDED WIRING

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**TC 1700**

AMENDMENT AND REQUEST FOR RECONSIDERATION

ASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

SIR:

Responsive to the Office Action of June 21, 2002, Applicants respectfully request reconsideration of the above-identified application in view of the following amendment and remarks.

REMARKS

Applicants thank Examiner Deo and the Examiner's Supervisor Benjamin Utech for the helpful and courteous discussion of July 18, 2002. During the discussion, the Examiner's Supervisor suggested that the submission of a Declaration providing a comparison of the polishing performance of the presently claimed invention with the polishing performance of the compositions disclosed in the Ronay patent may be sufficient for overcoming the rejection